

# MATERIAL DECLARATION SHEET



Material Number	PTVS15-076C-TH			
Product Line	Semiconductor Products			
Compliance Date	1 Aug 2012			
RoHS Compliant	Yes	MSL	N/A	

No.	Construction Element (subpart)	Homogenous Material	Material Weight (g)	Homogenous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart Mass % of total unit wt.
1	Encapsulation	Epoxy Resin	0.836600	Bisphenol Epoxy Resin	25068-38-6	38.00	5.70	14.99
				Brominated Epoxy Resin	26265-08-7	10.00	1.50	
				Crystalline Silica	14808-60-7	40.00	6.00	
				Antimony Trioxide	1309-64-4	3.00	0.45	
				Iron Oxide	1309-37-1	5.50	0.82	
				Titanium Oxide	13463-67-7	3.50	0.52	
2	Electrodes	Copper	3.525566	Copper	7440-50-8	99.10	62.59	63.16
				Silver	7440-22-4	0.40	0.25	
				Other	-	0.50	0.32	
3	Terminations	Copper	0.503299	Copper	7440-50-8	99.50	8.97	9.02
				Other	-	0.50	0.05	
4	Termination Finish	Silver	0.001821	Silver	7440-22-4	100.00	0.03	0.03
5	Chip	Silicon Die	0.319216	Silicon	7440-21-3	85.34	4.88	5.72
				Aluminium	7429-90-5	5.13	0.29	
				Nickel	7440-02-0	9.09	0.52	
				Gold	7440-57-5	0.44	0.03	
6	Die Attach	Solder	0.228614	Lead		92.50	3.79	4.10
				Tin	7440-31-5	5.00	0.20	
				Silver	7440-22-4	2.50	0.10	
7	Die Coating	Silicone	0.166711	Polysiloxane	na	22.11	0.66	2.99
				Chromium Sesquioxide	1308-38-9	5.67	0.17	
				Fumed Silica	112945-52-5	11.11	0.33	
				Filler	na	61.11	1.83	
Total Weight			5.581827					